

**$V_{RM} = 400\text{ V}$, $I_{F(AV)} = 20\text{ A}$, $t_{rr} = 50\text{ ns(max.)}$
Fast Recovery and High Power Diode
CTLD-4204S**

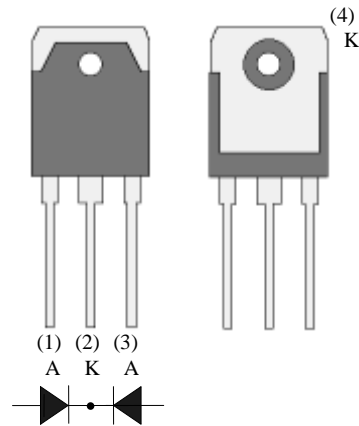
Features

The CTLD-4204S is a fast recovery diode which realize a peak reverse voltage of 400 V, a typical forward voltage drop of 1.25 V and typical trr of 22 ns optimizing a life-time control. It has the characteristics suit for PFC circuit of CCM.

The low thermal resistance package achieves high performance in terms of heat dissipation.

- V_{RM} ----- 400 V
- V_F ----- 1.4 V max. ($I_F = 10\text{ A}$)
- $I_{F(AV)}$ ----- 20 A
- t_{rr} ----- 50ns max.
($I_F = 500\text{ mA}$, $I_{RP} = 500\text{ mA}$, 90 % of R.P.)

Package
TO-3P-3L



Not to scale

Applications

- For PFC Circuit (CCM)
- For White Goods
- For Telecommunication Device, etc.

Absolute Maximum Ratings

- Unless otherwise specified, T_A is 25 °C

Parameter	Symbol	Rating	Unit	Notes
Peak Repetitive Reverse Voltage	V_{RM}	400	V	
Average Forward Current	$I_{F(AV)}$	20	A	
Surge Forward Current	I_{FSM}	100	A	10 ms Half sinewave, one shot
I^2t Limiting Value	I^2t	50	A^2s	$1\text{ ms} \leq t \leq 10\text{ ms}$
Junction Temperature	T_j	-40 to 150	°C	
Storage Temperature	T_{stg}	-40 to 150	°C	

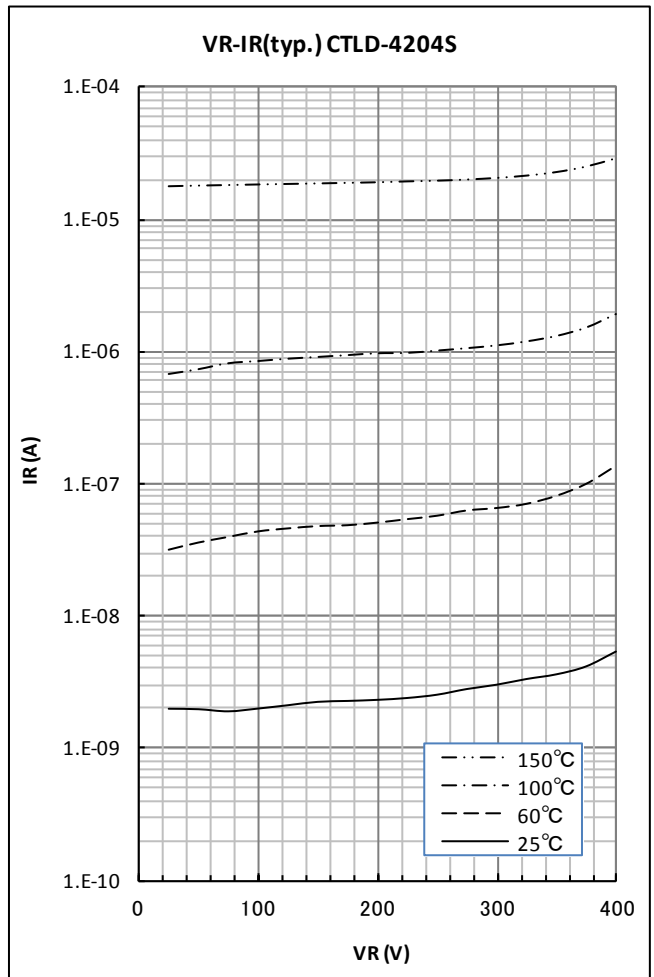
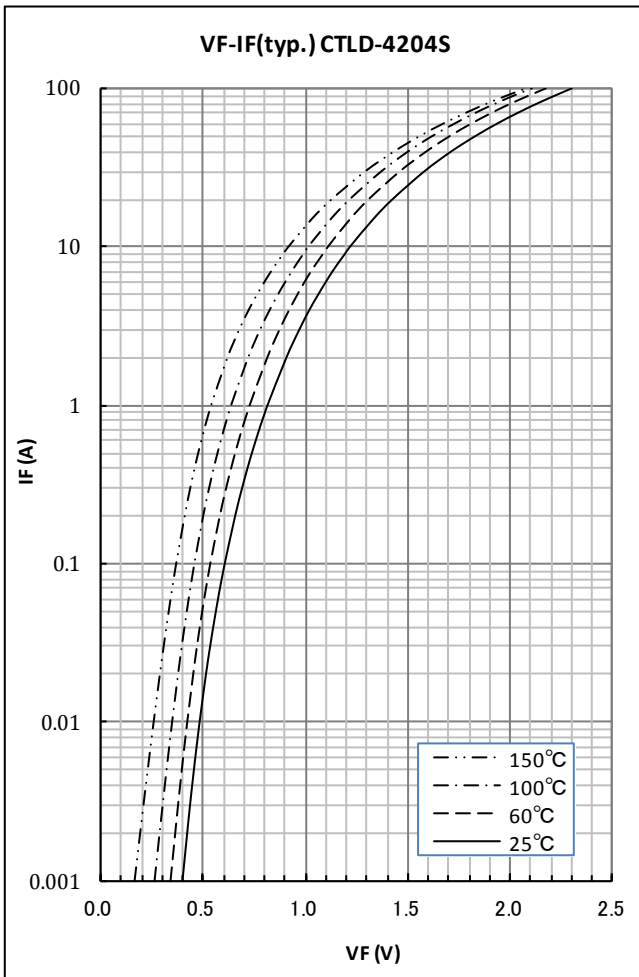
Electrical Characteristics

- Unless otherwise specified, T_A is 25 °C

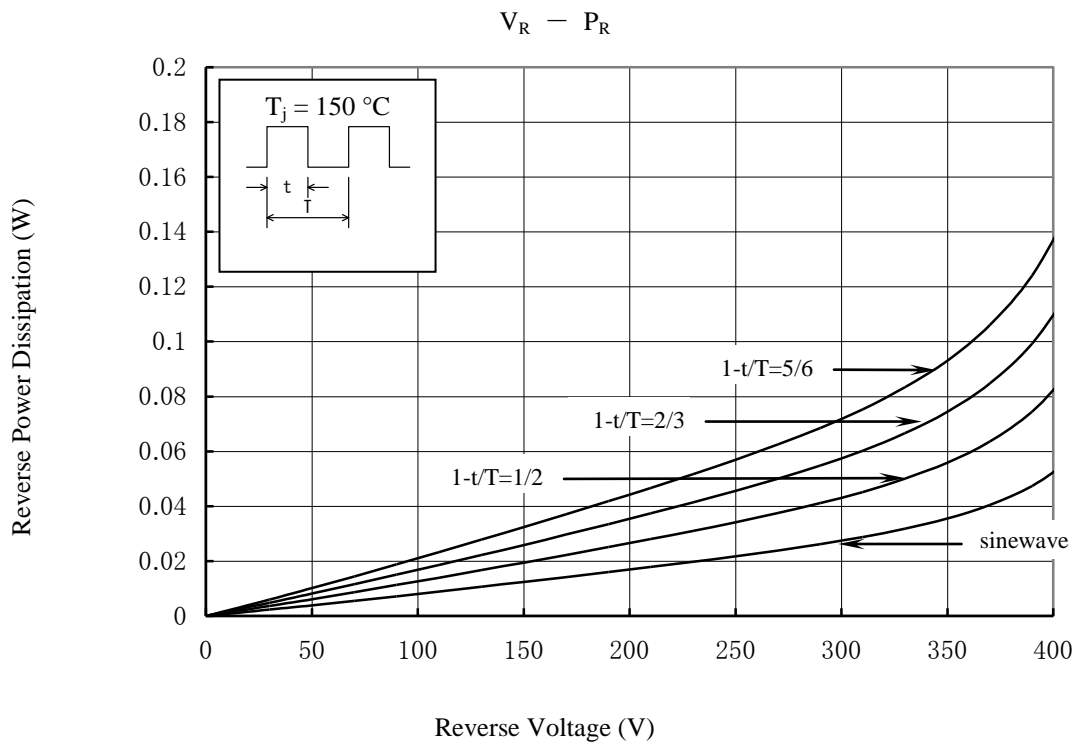
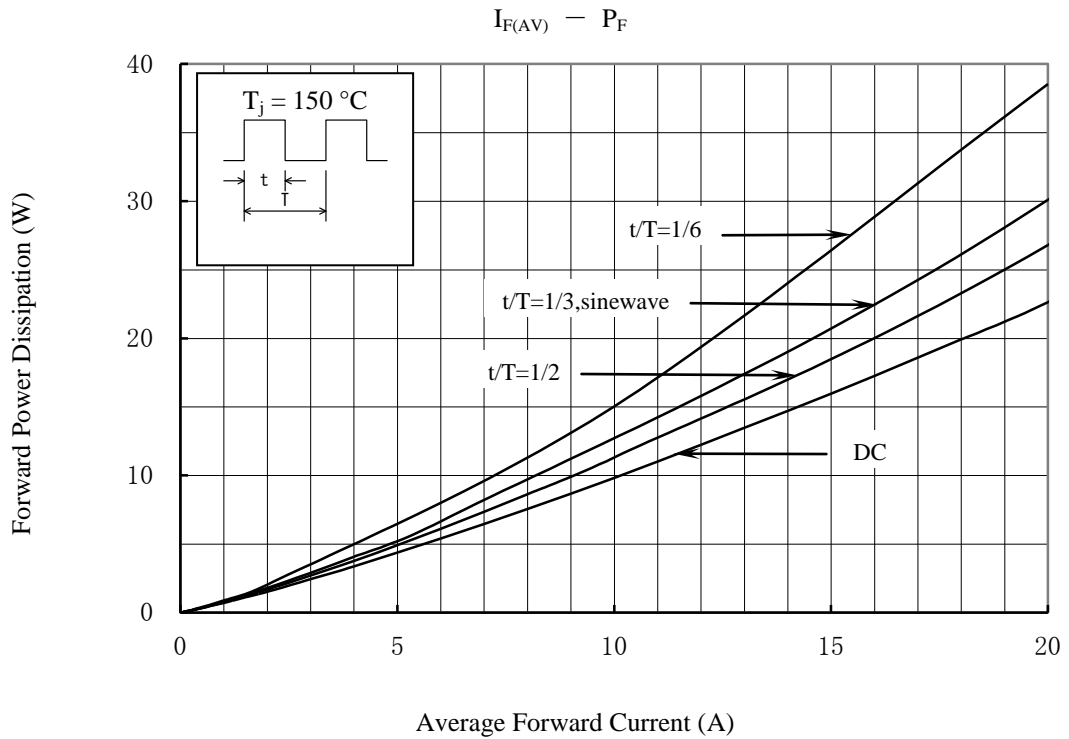
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Forward Voltage Drop	V_F	$I_F = 10\text{ A}$	—	1.25	1.4	V
Reverse Leakage Current	I_R	$V_R = V_{RM}$	—	—	20	μA
Reverse Leakage Current Under High Temperature	$H \cdot I_R$	$V_R = V_{RM}$, $T_j = 150\text{ °C}$	—	—	200	μA
Reverse Recovery Time	t_{rr}	$I_F = I_{RP} = 500\text{ mA}$, $T_j = 25\text{ °C}$, 90 % recovery point	—	22	50	ns
Thermal Resistance*	$R_{th(j-c)}$		—	—	2.0	°C/W

* $R_{th(j-c)}$ is thermal resistance between junction and case. Case temperature (T_C) is measured at the under of the screw hole of case.

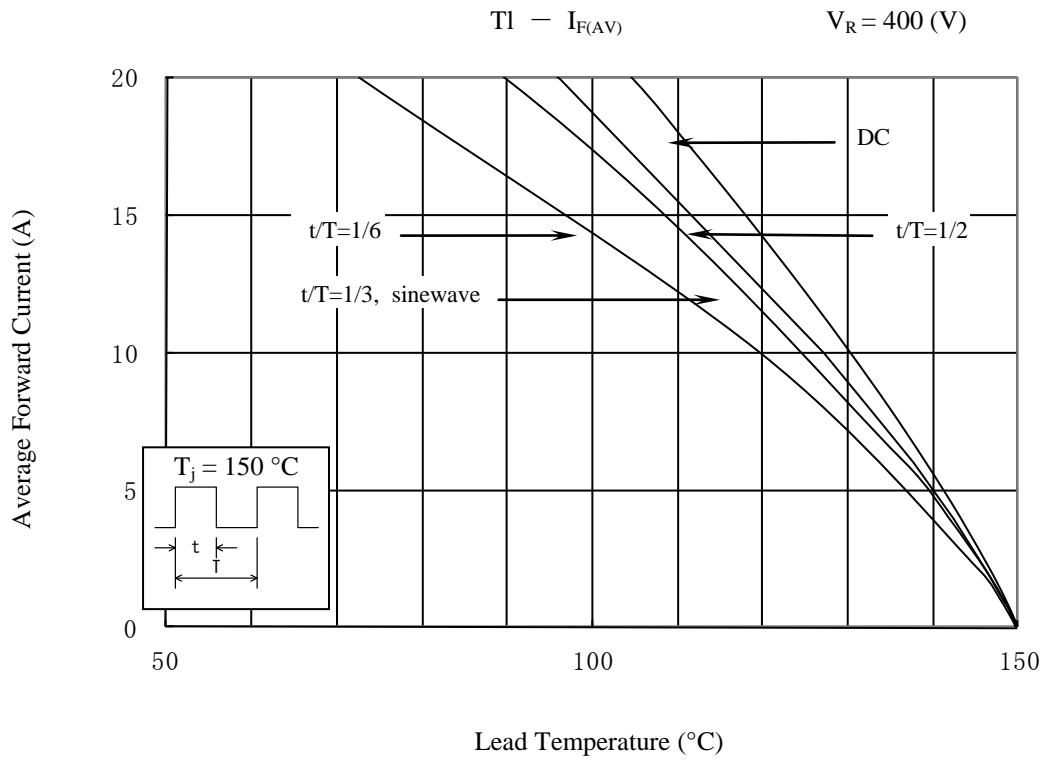
Performance Curves



Power Dissipation Curves



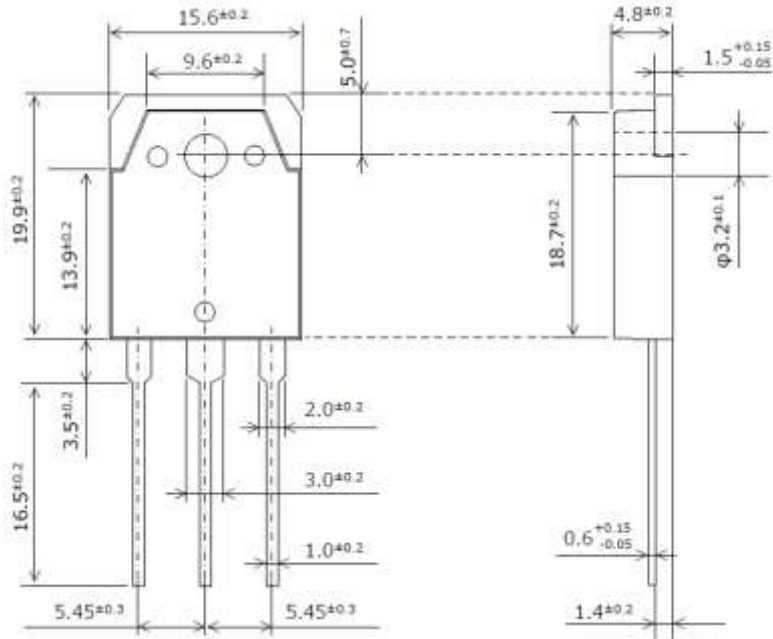
Derating Curves



CTLD-4204S

Package Outline

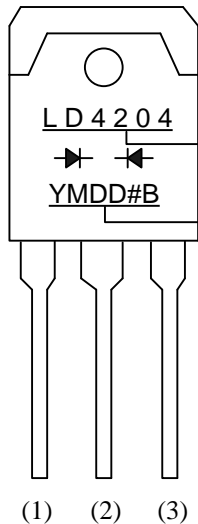
TO-3P-3L



NOTES:

- 1) Dimension is in millimeters
- 2) Pb-free. Device composition compliant with the RoHS directive

Marking Diagram



Part Number

Lot Number

Y is the Last digit of year (0 to 9)
 M is the Month (1 to 9, O, N or D)
 DD is the Date (two digit of 01 to 31)
 # is the last digit of wafer lot number
 B expresses Pb free pins

OPERATING PRECAUTIONS

In the case that you use Sanken products or design your products by using Sanken products, the reliability largely depends on the degree of derating to be made to the rated values. Derating may be interpreted as a case that an operation range is set by derating the load from each rated value or surge voltage or noise is considered for derating in order to assure or improve the reliability. In general, derating factors include electric stresses such as electric voltage, electric current, electric power etc., environmental stresses such as ambient temperature, humidity etc. and thermal stress caused due to self-heating of semiconductor products. For these stresses, instantaneous values, maximum values and minimum values must be taken into consideration. In addition, it should be noted that since power devices or IC's including power devices have large self-heating value, the degree of derating of junction temperature affects the reliability significantly.

Because reliability can be affected adversely by improper storage environments and handling methods, please observe the following cautions.

Cautions for Storage

- Ensure that storage conditions comply with the standard temperature (5 to 35°C) and the standard relative humidity (around 40 to 75%); avoid storage locations that experience extreme changes in temperature or humidity.
- Avoid locations where dust or harmful gases are present and avoid direct sunlight.
- Reinspect for rust on leads and solderability of the products that have been stored for a long time.

Cautions for Testing and Handling

When tests are carried out during inspection testing and other standard test periods, protect the products from power surges from the testing device, shorts between the product pins, and wrong connections. Ensure all test parameters are within the ratings specified by Sanken for the products.

Remarks About Using Silicone Grease with a Heatsink

- When silicone grease is used in mounting the products on a heatsink, it shall be applied evenly and thinly. If more silicone grease than required is applied, it may produce excess stress.
- Volatile-type silicone greases may crack after long periods of time, resulting in reduced heat radiation effect. Silicone greases with low consistency (hard grease) may cause cracks in the mold resin when screwing the products to a heatsink.

Our recommended silicone greases for heat radiation purposes, which will not cause any adverse effect on the product life, are indicated below:

Type	Suppliers
G746	Shin-Etsu Chemical Co., Ltd.
YG6260	Momentive Performance Materials Inc.
SC102	Dow Corning Toray Co., Ltd.

Cautions for Mounting to a Heatsink

- When the flatness around the screw hole is insufficient, such as when mounting the products to a heatsink that has an extruded (burred) screw hole, the products can be damaged, even with a lower than recommended screw torque. For mounting the products, the mounting surface flatness should be 0.05mm or less.
- Please select suitable screws for the product shape. Do not use a flat-head machine screw because of the stress to the products. Self-tapping screws are not recommended. When using self-tapping screws, the screw may enter the hole diagonally, not vertically, depending on the conditions of hole before threading or the work situation. That may stress the products and may cause failures.
- Recommended screw torque:

Package	Recommended Screw Torque
TO-220, TO-220F	0.490 to 0.686 N·m (5 to 7 kgf·cm)
TO-3P, TO-3PF, TO-247	0.686 to 0.882 N·m (7 to 9 kgf·cm)
SLA	0.588 to 0.784 N·m (6 to 8 kgf·cm)

- For tightening screws, if a tightening tool (such as a driver) hits the products, the package may crack, and internal stress fractures may occur, which shorten the lifetime of the electrical elements and can cause catastrophic failure. Tightening with an air driver makes a substantial impact. In addition, a screw torque higher than the set torque can be applied and the package may be damaged. Therefore, an electric driver is recommended. When the package is tightened at two or more places, first pre-tighten with a lower torque at all places, then tighten with the specified torque. When using a power driver, torque control is mandatory.

- Please pay special attention about the slack of the press mold. In case that the hole diameter of the heatsink is less than 4 mm, it may cause the resin crack at tightening.

Soldering

- When soldering the products, please be sure to minimize the working time, within the following limits:
 - 260 ± 5 °C 10 ± 1 s (Flow, 2 times)
 - 380 ± 10 °C 3.5 ± 0.5 s (Soldering iron, 1 time)
- Soldering should be at a distance of at least 1.5 mm from the body of the products.

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